IN THE SPECIFICATION:

Please replace the paragraph beginning at page 2, line 2 with the following rewritten paragraph:

-- This application is a divisional of U.S. Patent Application Serial No. 09/387,640, filed on August 31, 1999, now U.S. Patent No. 6,424,033 B1, which is incorporated herein by reference. --

Please replace the paragraph beginning at page 9, line 15 with the following rewritten paragraph:

-- Figure 1 is an elevational cross-section view of an IC chip package 10 with a board-on-chip (BOC) configuration. Figure 1 illustrates an IC chip 12 disposed upon a substrate 14 such as a flexible PCB. The active surface 16 of IC chip 12 is disposed against a first side 50 of substrate 14. Emerging from the active surface 16 of IC chip 12, are bond wires 18 that act as electrical connectors between active surface 16 of IC chip 12 and substrate 14. --